

1. Description

The HS20P06DA is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

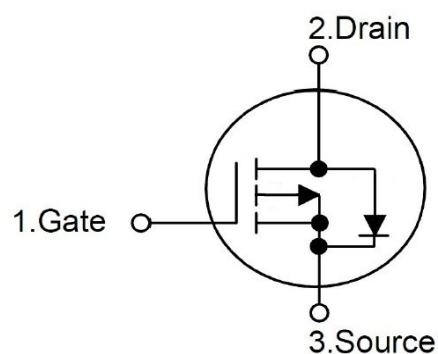
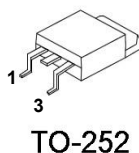
2. Feature

- $R_{DS(ON)} \leq 78m\Omega @ V_{GS} = -10V$
- $R_{DS(ON)} \leq 100m\Omega @ V_{GS} = -4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

V_{DS}	-60	V
$R_{DS(on)}$	78	$m\Omega$
I_D	-17.7	A

3. Pin configuration

Order Number	Package
HS20P06DA	TO-252



4. Absolute maximum ratings (TC= 25 °C, unless otherwise specified)

Parameter	Symbol	Ratings	Units	
Drain-source voltage	V_{DSS}	-60	V	
Gate-source voltage	V_{GSS}	±20	V	
Continuous Drain Current ($T_j=150^{\circ}C$)	I_D	$T_c =25^{\circ}C$	-17.7	A
		$T_c =70^{\circ}C$	-14.1	A
Drain current pulsed	I_{DP}	-71	A	
Maximum Power Dissipation	P_D	$T_c=25^{\circ}C$	39.1	W
		$T_c=70^{\circ}C$	25	W
Junction temperature	T_J	+150	°C	
Storage temperature	T_{STG}	-50~+150	°C	

5. Thermal characteristics

Parameter	Symbol	Ratings	Units
Thermal resistance, case to sink typ	R_{thCS}	0.5	°C/W
Thermal resistance junction to case	R_{thJC}	3.2	°C/W

6. Electrical characteristics (T_J=25°C, unless otherwise specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
STATIC						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250 μA	-60			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250 μA	-1		-3	V
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±20V			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-60V, V _{GS} =0V			1	μA
R _{DS(ON)}	Drain-Source On-State Resistance ^a	V _{GS} =-10V, I _D = -20A		65	78	mΩ
		V _{GS} =-4.5V, I _D = -16A		80	100	
V _{SD}	Diode Forward Voltage	I _S =-20A, V _{GS} =0V		1	1.2	V
DYNAMIC						
Q _g	Total Gate Charge(10V)	V _{DS} =-30V, V _{GS} =-10V, I _D =-20A		22		nC
Q _g	Total Gate Charge(4.5V)	V _{DS} =-30V, V _{GS} =-4.5V, I _D =-20A		10		
Q _{gs}	Gate-Source Charge			6.3		
Q _{gd}	Gate-Drain Charge			5		
C _{iss}	Input capacitance	V _{DS} =-15V, V _{GS} =0V, F=1MHz		958		pF
C _{oss}	Output Capacitance			100		
C _{rss}	Reverse Transfer Capacitance			33		
t _{d(on)}	Turn-On Delay Time	V _{DS} =-15V, R _L =15Ω I _D =-1A, V _{GEN} =-10V, R _G =3Ω		36		ns
t _r	Turn-On Rise Time			16		
t _{d(off)}	Turn-Off Delay Time			53		
t _f	Turn-On Fall Time			6		

Note :a. Pulse test: pulse width 300μs, duty cycle 2% , Guaranteed by design , not subject to production testing.

b. Homsemi reserves the right to improve product design , functions and reliability without notice.